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Semiconductor Packaging Materials 2017 Global Market Expected to Grow at CAGR of 4.33% and Forecast to 2021

Wiseguyreports.Com Publish New Research Report On -"Semiconductor Packaging Materials 2017 Global Market Expected to Grow at CAGR of 4.33% and Forecast to 2021"

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Semiconductor Packaging Materials Market 2017

Semiconductor packaging materials comprise metals, plastic, and ceramic components. They not only protect the IC on the semiconductor die, but also interconnect the die and the PCB. They protect the die from external mechanical impacts and corrosion, and also act as an electrically conductive interconnects with excellent signal propagation properties. Excessive heat in the circuits is dissipated through heat spreaders. Packaging components vary in dimensions and functionality.

The analysts forecast the Global Semiconductor Packaging Materials market to grow at a CAGR of 4.33 percent over the period 2014-2019.

Covered in this Report
The Global Semiconductor Packaging Materials market can be divided into seven segments based on the type of product: Organic Substrates, Bonding Wires, Leadframes, Encapsulation Resins, Ceramic Packages, Die Attach Materials, and Other Semiconductor Packaging Materials. The key consumers of these packaging materials are the Electronics Industry, the Semiconductor Industry, and the Automotive Sector.

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The report, Global Semiconductor Packaging Materials Market 2015-2019, has been prepared based on an in-depth market analysis with inputs from industry experts. The report covers the APAC region, North America, and Europe; it also covers the Global Semiconductor Packaging Materials market landscape and its growth prospects over the coming years. The report also includes a discussion of the key vendors operating in this market.

Key Regions
- APAC
- Europe
- North America

Key Vendors
- Alent
- BASF
- Henkel
- Hitachi Chemical
- Kyocera

Other Prominent Vendors
- Beijing Doublink Solders
- Beijing Kehua New Chemical Technology
- Cheil Industries
- Diehl Metall
- Duksan Hi-metal
- DuPont
- Dynacraft
- Evergreen Semiconductor Materials
- Guangdong Rongtai
- Heesung Metal
- Heraeus
- Honeywell Electronic Materials
- Ibiden
- Indium
- IQE
- KCC
- LG Innotek
- Lintec
- Lord
- Mitsui High-Tec
- MK Electron
- Nanya PCB
- Ningbo Dongsheng IC
- Nippon Micrometal

Key Market Driver
- Surge in Sales of Smartphones and Smart Devices
- For a full, detailed list, view our report

Key Market Challenge
- High Dependency on Performance of Semiconductor Equipment Industry
- For a full, detailed list, view our report

Key Market Trend
- Popularity of Redistributed Chip Packaging
- For a full, detailed list, view our report

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